

**BID RELEASE**

**FOXCONN®**



# Fii Smart Manufacturing Center Bid Package #02 - MEP



**The MEP Bid Package #02 for the Fii Smart Manufacturing Center is now available.**

**BID PACKAGE #02**

Contract No. 23	Mechanical
Contract No. 24	Plumbing
Contract No. 25	Fire Protection
Contract No. 26	Electrical

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## **Non-Disclosure Agreement – NDA:**

The Mortenson NDA must be signed and returned to Mortenson to participate in this bid invitation and to attend the pre-bid meeting. The NDA will be issued through our Building Connected website after any firm registers through the link provided below.

## **About the Project:**

The project consists of construction of the core and shell of 230,000 SF Fii Smart Manufacturing Center. This includes sitework, site improvements, structure and enclosure systems.

Procurement of Subcontractors, Suppliers, Vendors, and Professional Services will follow the clear and detailed process of the Wisconsin First program.

## **Registration and Bid Information:**

To receive project information, please register via the link below:

<https://bit.ly/2k9Qn5V>

After your firm has registered, a Building Connected invitation will be emailed to the email address provided within one business day. If you do not receive the invitation or have trouble, please email both [denise.fahrnow@mortenson.com](mailto:denise.fahrnow@mortenson.com) and [ross.bunchek@mortenson.com](mailto:ross.bunchek@mortenson.com)

A prebid meeting will be held on Thursday, 10/24/19. The NDA must be executed to attend. More information on the pre-bid is posted on Building Connected

## **Information and Resources:**

[Wisconvalley.wi.gov](http://Wisconvalley.wi.gov)